



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ22DN20NS3 G	Issued	24. February 2022
MA#	MA005709197		
Package	PG-TSDSON-8-37	Weight*	35.67 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.451	1.26	1.26	12636	12636
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		99	
	non noble metal	zinc	7440-66-6	0.014	0.04		397	
	non noble metal	iron	7439-89-6	0.283	0.79		7944	
	non noble metal	copper	7440-50-8	11.505	32.25	33.09	322542	330982
wire	noble metal	gold	7440-57-5	0.035	0.10	0.10	989	989
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1068	
	plastics	epoxy resin	-	1.962	5.50		55005	
	inorganic material	silicondioxide	60676-86-0	17.049	47.81	53.42	477960	534033
leadfinish	non noble metal	tin	7440-31-5	0.370	1.04	1.04	10375	10375
plating	noble metal	silver	7440-22-4	0.081	0.23	0.23	2265	2265
solder	non noble metal	tin	7440-31-5	0.012	0.03		344	
	noble metal	silver	7440-22-4	0.015	0.04		430	
	non noble metal	lead	7439-92-1	0.585	1.64	1.71	16410	17184
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		110	
	non noble metal	iron	7439-89-6	0.078	0.22		2197	
	non noble metal	copper	7440-50-8	3.182	8.92	9.15	89202	91536
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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